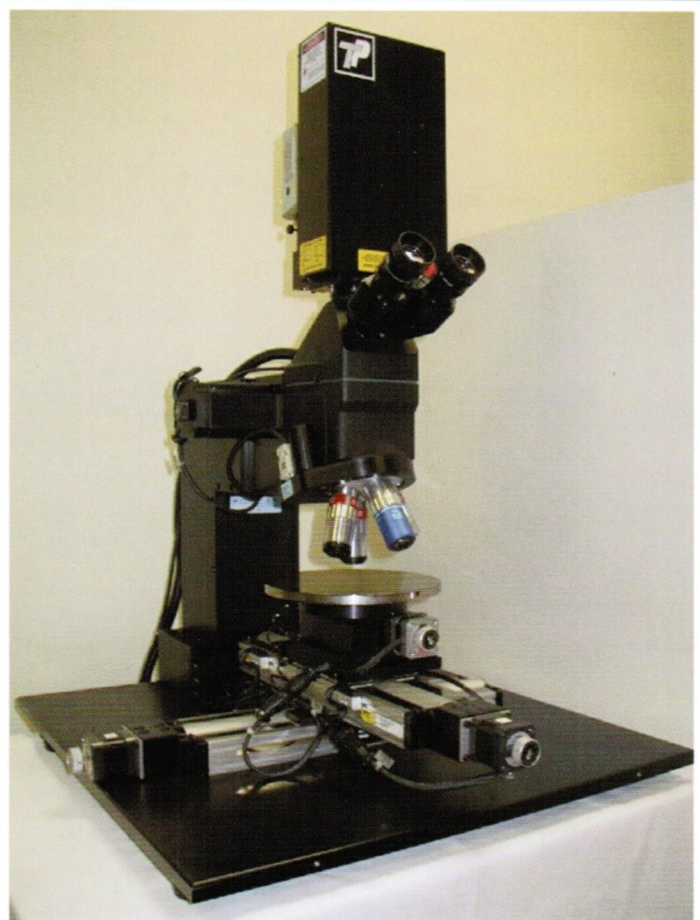
Model LRS-2400

Extremely compact, versatile, easy to use with user-friendly software, the Model LRS-2400 is available in both table top and console configurations.

Inspection Systems generate defect data files and from these data files, engineers have to locate the physical defect for further study. The task becomes impossible or unbearable when dealing with large wafers or large dies that have sub-micron features.

LRS-2400 reads the defect data and navigates to the exact location of the defect. With a high power microscope the user can perform tasks as highlighted in feature section below.

Using a simple, compact, triple wavelength Nd:Yag Laser system, the Model LRS-2400 performs laser cutting operations for design verification, wafer failure analysis and repair.



Model LRS-2400 for 8" Wafer with Laser Marking and Defect File Read/Navigate

LRS-2400 Features.

Standard Configuration:	Other features:
• Review defects with auto-search • Re-classify defect categories With Laser Option: • Re-locate defect in SEM/FIB • Repair defects.	• Built-in frame grabber • Defect data formats available: o KLA-Tencor: KLARF, TFF • Flexible script language • Remote interface facilities • Probing platform ready

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After reviewing the defect under a high-power microscope, if further analysis is required, the next step for a FA engineer is to do a cross section and study the defects. The problem faced, in most cases, is to get back to the exact defect location in a FIB, for cross sectioning, or in a SEM for further study. It could take considerable time, if even possible, to locate the defects. Time and money spent in doing cross sectioning is a costly proposition that most users want to avoid. The solution: Laser Marking.

The LSR-2400 reads the defect data and navigates to the exact location of the defect. The user would then activate the top mounted Laser to mark the location. The laser marks would be easily spotted under FIB/SEM low magnification setting. Set the marks at the center field of view then zoom in, the FIB/SEM operator will then be able to get to the exact defect location in seconds…

Specifications

Stage:

Travel distance	8" x 8" up to 12" x 12"
Accuracy	+/-5µm
Resolution	1µm
Chuck diameter	8" up to 12"

Computer:

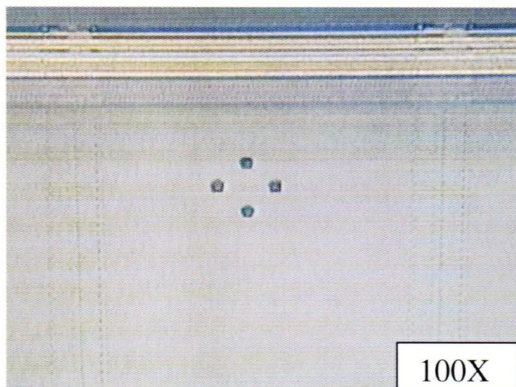
- Latest Processor with plenty of RAM for fast image processing.
- Built-in Frame Grabber with image capture facilities in various formats.

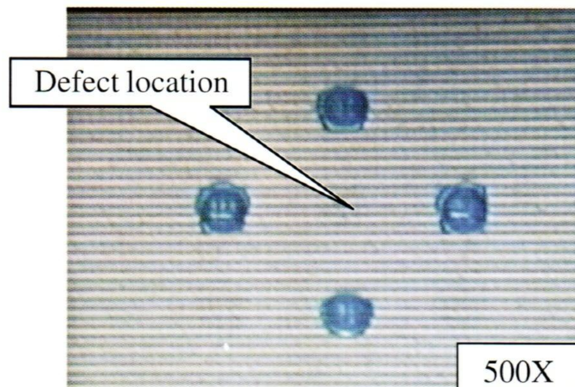
Laser Head

Wavelength	1064/355/532 nm Nd: YAG Laser
Pulse Width	7 nanosecond
Energy	.6mJ
Cooling	Ambient Air
Beam Mode	TEMoo (SingleMode)

Cutting Size:

50X Objective:	50 x 50 µm Max. 1.2 x 1.2 µm Min.
100X Objective:	20 x 20 µm Max. 0.6 x 0.6 µm Min.





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